+357 96 030922
info@marketpublishers.com

Global Radiation Fins for Automotive Power Semiconductors Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

https://marketpublishers.com/r/RED1F8A15039EN.html
Date: January 2026
Pages: 123
Price: US$ 3,480.00 (Single User License)
ID: RED1F8A15039EN

Abstracts

According to our (Global Info Research) latest study, the global Radiation Fins for Automotive Power Semiconductors market size was valued at US$ 377 million in 2025 and is forecast to a readjusted size of US$ 951 million by 2032 with a CAGR of 13.4% during review period.

Radiation fins for automotive power semiconductors are air-side thermal structures used with MOSFETs, IGBTs, rectifiers, and power modules. By maximizing surface area via straight fins, pin fins, etc., they conduct heat from the device/base into the fin field and dissipate it to ambient air through convection (natural or forced) and radiation, typically used together with thermal interface materials and, when needed, fans/ducting to meet power density and reliability targets.

Upstream includes aluminum/copper feedstock, surface finishing (anodizing, plating), TIMs (grease/phase-change pads/insulators), fasteners and fans. Midstream covers heatsink/fin manufacturing followed by cutting, CNC, finishing and thermal/airflow characterization. Downstream customers are device and power-module makers and power-electronics system OEMs (inverters, OBC/DC-DC, industrial drives, UPS/chargers) that integrate the heatsink into the mechanical and thermal design and qualify it for reliability.

In 2025, global radiation fins for automotive power semiconductorproduction reached approximately 36 million units, with an average global market price is $10 per unit.

This report is a detailed and comprehensive analysis for global Radiation Fins for Automotive Power Semiconductors market. Both quantitative and qualitative analyses

+357 96 030922
info@marketpublishers.com

are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Radiation Fins for Automotive Power Semiconductors market size and forecasts, in consumption value ($ Million), sales quantity (K Units), and average selling prices (US$/Unit), 2021-2032

Global Radiation Fins for Automotive Power Semiconductors market size and forecasts by region and country, in consumption value ($ Million), sales quantity (K Units), and average selling prices (US$/Unit), 2021-2032

Global Radiation Fins for Automotive Power Semiconductors market size and forecasts, by Type and by Application, in consumption value ($ Million), sales quantity (K Units), and average selling prices (US$/Unit), 2021-2032

Global Radiation Fins for Automotive Power Semiconductors market shares of main players, shipments in revenue ($ Million), sales quantity (K Units), and ASP (US$/Unit), 2021-2026

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries
To assess the growth potential for Radiation Fins for Automotive Power Semiconductors
To forecast future growth in each product and end-use market
To assess competitive factors affecting the marketplace

This report profiles key players in the global Radiation Fins for Automotive Power Semiconductors market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Huangshan Googe, Heatsink Advanced Materials, Kunshan Gootage Thermal Technology, Dana Incorporated, Jentech Precision Industrial, Amulaire Thermal Technology, TAIWA CO., Ltd., Wieland Microcool, Jiangyin Saiying Electron, Suzhou Haoli Electronic

+357 96 030922
info@marketpublishers.com

Technology, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Radiation Fins for Automotive Power Semiconductors market is split by Type and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Pin-fin Baseplate

Flat Baseplate

Market segment by Module

IGBT Module

SiC MOSFET Module

Market segment by Material

Cu Baseplate

AlSIC Baseplate

Other

Market segment by Application

BEV

+357 96 030922
info@marketpublishers.com

PHEV

Major players covered

Huangshan Googe

Heatsink Advanced Materials

Kunshan Gootage Thermal Technology

Dana Incorporated

Jentech Precision Industrial

Amulaire Thermal Technology

TAIWA CO., Ltd.

Wieland Microcool

Jiangyin Saiying Electron

Suzhou Haoli Electronic Technology

Sitritec Thermal Control Materials

Market segment by region, regional analysis covers
North America (United States, Canada, and Mexico)
Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)
Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)
South America (Brazil, Argentina, Colombia, and Rest of South America)
Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

+357 96 030922
info@marketpublishers.com

Chapter 1, to describe Radiation Fins for Automotive Power Semiconductors product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Radiation Fins for Automotive Power Semiconductors, with price, sales quantity, revenue, and global market share of Radiation Fins for Automotive Power Semiconductors from 2021 to 2026.

Chapter 3, the Radiation Fins for Automotive Power Semiconductors competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Radiation Fins for Automotive Power Semiconductors breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2021 to 2032.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2021 to 2032.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2021 to 2026.and Radiation Fins for Automotive Power Semiconductors market forecast, by regions, by Type, and by Application, with sales and revenue, from 2027 to 2032.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Radiation Fins for Automotive Power Semiconductors.

Chapter 14 and 15, to describe Radiation Fins for Automotive Power Semiconductors sales channel, distributors, customers, research findings and conclusion.

+357 96 030922
info@marketpublishers.com

Contents

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

3 COMPETITIVE ENVIRONMENT: RADIATION FINS FOR AUTOMOTIVE POWER SEMICONDUCTORS BY MANUFACTURER

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

16 APPENDIX

+357 96 030922
info@marketpublishers.com

List Of Tables

LIST OF TABLES

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

List Of Figures

LIST OF FIGURES

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

I would like to order

Product name: Global Radiation Fins for Automotive Power Semiconductors Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

Product link: https://marketpublishers.com/r/RED1F8A15039EN.html

Price: US$ 3,480.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:
info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/RED1F8A15039EN.html